

TOSHIBA CMOS DIGITAL INTEGRATED CIRCUIT SILICON MONOLITHIC

**TC74HC540AP, TC74HC540AF, TC74HC540AFW
TC74HC541AP, TC74HC541AF, TC74HC541AFW****OCTAL BUS BUFFER****TC74HC540AP / AF / AFW INVERTING , 3 - STATE OUTPUTS
TC74HC541AP / AF / AFW NON - INVERTING , 3 - STATE OUTPUTS**

The TC74HC540A/TC74HC541A are high speed CMOS OCTAL BUS BUFFERs fabricated with silicon gate C²MOS technology.

They achieve the high speed operation similar to equivalent LSTTL while maintaining the CMOS low power dissipation.

The TC74HC540A is an inverting type, and the TC74HC541A is a non-inverting type.

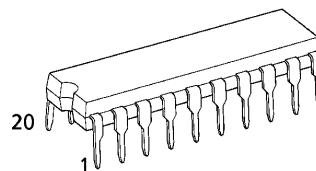
When either \bar{G}_1 or \bar{G}_2 are high, the terminal outputs are in the high-impedance state.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

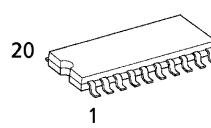
FEATURES :

- High Speed..... $t_{pd} = 10\text{ns}(\text{typ.})$ at $V_{CC} = 5\text{V}$
- Low Power Dissipation..... $I_{CC} = 4\mu\text{A}(\text{Max.})$ at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{NIH} = V_{NIL} = 28\% V_{CC}$ (Min.)
- Output Drive Capability..... 15 LSTTL Loads
- Symmetrical Output Impedance..... $|I_{OH}| = I_{OL} = 6\text{mA}(\text{Min.})$
- Balanced Propagation Delays..... $t_{pLH} \approx t_{pHL}$
- Wide Operating Voltage Range..... V_{CC} (opr.) = $2\text{V} \sim 6\text{V}$
- Pin and Function Compatible with 74LS540/541

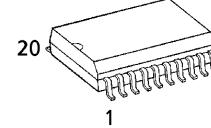
(Note) The JEDEC SOP (FW) is not available in Japan.



P (DIP20-P-300-2.54A)
Weight : 1.30g (Typ.)



F (SOP20-P-300-1.27)
Weight : 0.22g (Typ.)



FW (SOL20-P-300-1.27)
Weight : 0.46g (Typ.)

TRUTH TABLE

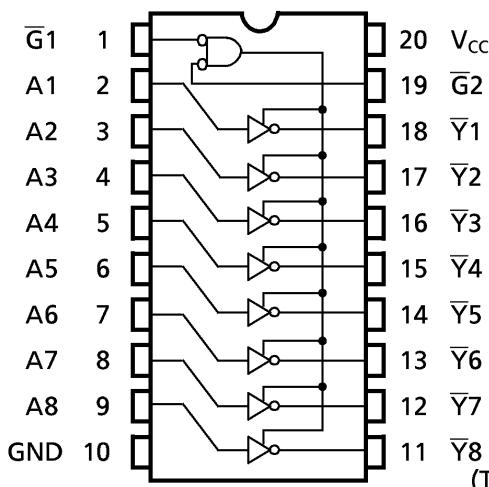
INPUTS			OUTPUTS	
\bar{G}_1	\bar{G}_2	A_n	Y_n^*	\bar{Y}_n^*
H	X	X	Z	Z
X	H	X	Z	Z
L	L	H	H	L
L	L	L	L	H

X : Don't Care

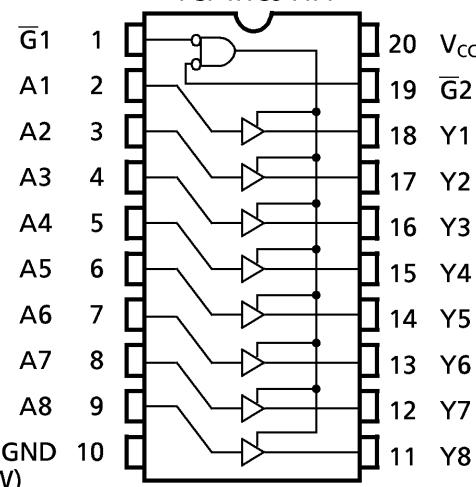
Z : High Impedance

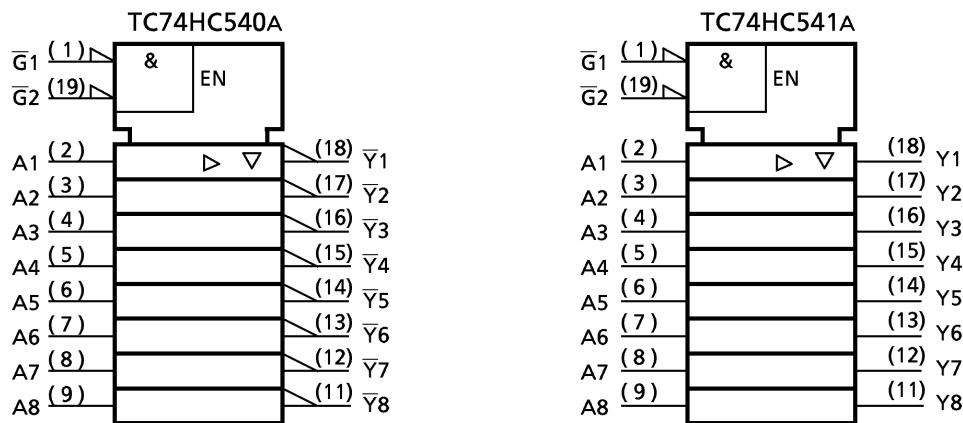
* : Y_n HC541 \bar{Y}_n HC540**PIN ASSIGNMENT**

TC74HC540A



TC74HC541A



IEC LOGIC SYMBOL

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	-0.5~7	V
DC Input Voltage	V_{IN}	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 20	mA
DC Output Current	I_{OUT}	± 35	mA
DC V_{CC} /Ground Current	I_{CC}	± 75	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP)	mW
Storage Temperature	T_{STG}	-65~150	°C

*500mW in the range of $T_a = -40^{\circ}\text{C} \sim 65^{\circ}\text{C}$. From $T_a = 65^{\circ}\text{C}$ to 85°C a derating factor of $-10\text{mW}/^{\circ}\text{C}$ shall be applied until 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2~6	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{OPR}	-40~85	°C
Input Rise and Fall Time	t_r, t_f	0~ 1000 ($V_{CC} = 2.0\text{V}$) 0~ 500 ($V_{CC} = 4.5\text{V}$) 0~ 400 ($V_{CC} = 6.0\text{V}$)	ns

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V_{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT
				MIN.	TYP.	MAX.	MIN.	MAX.	
High - Level Input Voltage	V_{IH}		2.0 4.5 6.0	1.50 3.15 4.20	— — —	— — —	1.50 3.15 4.20	— — —	V
Low - Level Input Voltage	V_{IL}		2.0 4.5 6.0	— — —	— — —	— — —	0.50 1.35 1.80	— — —	V
High - Level Output Voltage	V_{OH}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -20\mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	2.0 4.5 6.0	— — —	1.9 4.4 5.9	— — —
			$I_{OH} = -6\text{ mA}$ $I_{OH} = -7.8\text{ mA}$	4.5 6.0	4.18 5.68	4.31 5.80	— —	4.13 5.63	— —
Low - Level Output Voltage	V_{OL}	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 20\mu\text{A}$	2.0 4.5 6.0	— — —	0.0 0.0 0.0	0.1 0.1 0.1	— — —	0.1 0.1 0.1
			$I_{OL} = 6\text{ mA}$ $I_{OL} = 7.8\text{ mA}$	4.5 6.0	— —	0.17 0.18	0.26 0.26	— —	0.33 0.33
3 - State Output Off - State Current	I_{OZ}	$V_{IN} = V_{IH}$ or V_{IL} $V_{OUT} = V_{CC}$ or GND	6.0	—	—	± 0.5	—	± 5.0	μA
Input Leakage Current	I_{IN}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	± 0.1	—	± 1.0	
Quiescent Supply Current	I_{CC}	$V_{IN} = V_{CC}$ or GND	6.0	—	—	4.0	—	40.0	

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 6\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	CL (pF)	V_{CC} (V)	$T_a = 25^\circ\text{C}$			$T_a = -40\text{--}85^\circ\text{C}$		UNIT
					MIN.	TYP.	MAX.	MIN.	MAX.	
Output Transition Time	t_{TLH}		50	2.0	—	25	60	—	75	ns
	t_{THL}			4.5	—	7	12	—	15	
				6.0	—	6	10	—	13	
Propagation Delay Time	t_{pLH}		50	2.0	—	36	90	—	115	ns
				4.5	—	12	18	—	23	
				6.0	—	10	15	—	20	
	t_{pHL}		150	2.0	—	51	130	—	165	
				4.5	—	17	26	—	33	
				6.0	—	14	22	—	28	
Output Enable Time	t_{pZL}	$R_L = 1\text{k}\Omega$	50	2.0	—	45	125	—	155	ns
				4.5	—	14	25	—	31	
				6.0	—	12	21	—	26	
	t_{pZH}		150	2.0	—	60	165	—	205	
				4.5	—	19	33	—	41	
				6.0	—	16	28	—	35	
Output Disable time	t_{pLZ}	$R_L = 1\text{k}\Omega$	50	2.0	—	40	125	—	155	pF
	t_{pHZ}			4.5	—	16	25	—	31	
				6.0	—	14	21	—	26	
Input Capacitance	C_{IN}				—	5	10	—	10	pF
Output Capacitance	C_{OUT}				—	10	—	—	—	
Power Dissipation Capacitance	$C_{PD}(1)$	TC74HC540A			—	32	—	—	—	
		TC74HC541A			—	35	—	—	—	

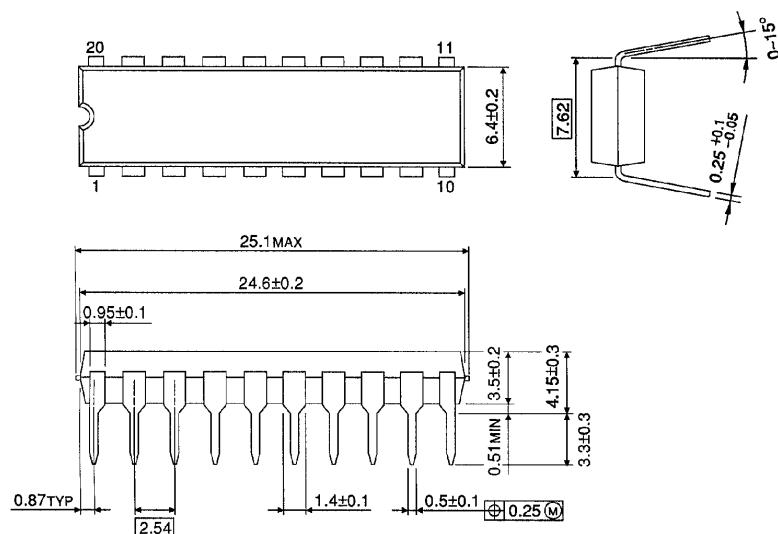
Note (1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

$$I_{CC(\text{opr})} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 \text{ (per bit)}$$

DIP 20PIN PACKAGE DIMENSIONS (DIP20-P-300-2.54A)

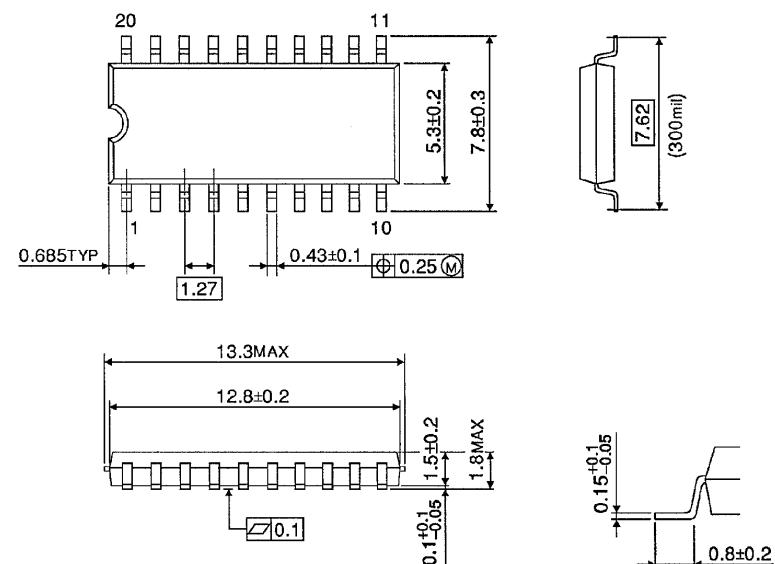
Unit in mm



Weight : 1.30g (Typ.)

SOP 20PIN (200mil BODY) PACKAGE DIMENSIONS (SOP20-P-300-1.27)

Unit in mm

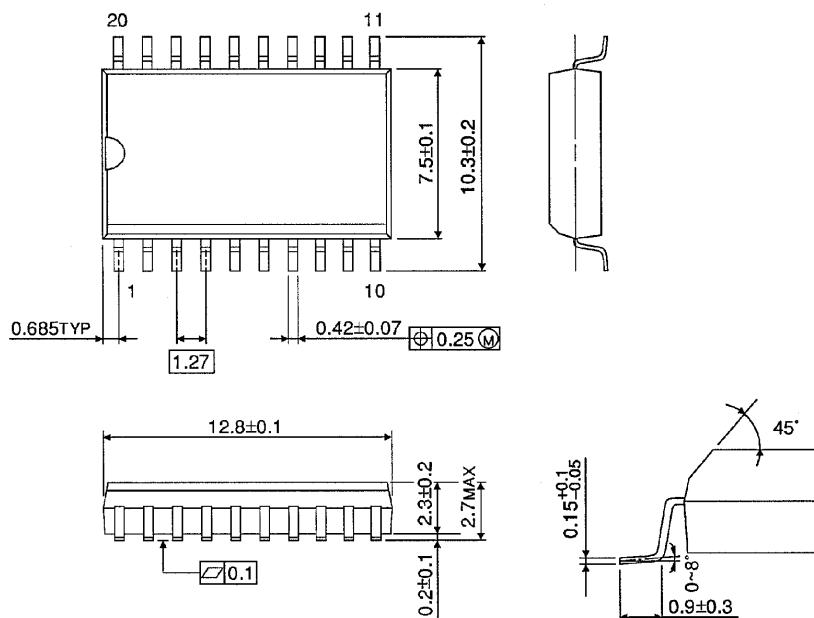


Weight : 0.22g (Typ.)

SOP 20PIN (300mil BODY) PACKAGE DIMENSIONS (SOL20-P-300-1.27)

Unit in mm

(Note) This package is not available in Japan.



Weight : 0.46g (Typ.)

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